

Integration of Electrodeposited Ni-Fe in MEMS with Low-Temperature Deposition and Etch Processes

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The data represented in figures 7, 8, 9, 14c, and 14f of the manuscript is available in the Excel file enclosed. The spreadsheet is divided into tabs corresponding to the different figures in the manuscript, as follows.

Figure 7 – “Figure 7” tab in the Excel file

Column A contains the measurement time in seconds.

Column B contains the average etched thickness in nm. This is calculated as difference between the average measured thickness at a specific time and the average measured thickness at time equal 0.

Column C contains the dispersion of the measurement. This is calculated as the difference between the maximum and minimum thickness values measured across different locations on the wafer and different repetitions.

Figure 8 – “Figure 8” tab in the Excel file

Column A contains the measurement time in minutes.

Column B contains the average etched thickness in nm. This is calculated as difference between the average measured thickness at a specific time and the average measured thickness at time equal 0.

Column C contains the dispersion of the measurement. This is calculated as the difference between the maximum and minimum thickness values measured across different locations on the wafer and different repetitions.

Figure 9 – “Figure 9” tab in the Excel file

Column A contains the measurement time in minutes.

Column B contains the average etched thickness in nm. This is calculated as difference between the average measured thickness at a specific time and the average measured thickness at time equal 0.

Column C contains the dispersion of the measurement. This is calculated as the difference between the maximum and minimum thickness values measured across different locations on the wafer and different repetitions.

Figure 14c – “Figure 14c” tab in the Excel file

Column A contains the scan distance in mm.

Column B contains the profile height in μm measured across the scan line of *column A*.

Figure 14f – “Figure 14f” tab in the Excel file

Column A contains the scan distance in mm.

Column B contains the profile height in μm measured across the scan line of *column A*.